Call for Abstracts (due March 8, 2021)

ASME 2021 INTERPACK®

International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

Date: Oct. 26-28, 2021

http://event.asme.org/interpack

InterPACK is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics and photonics packaging and heterogeneous integration. It is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of the meeting has been highly beneficial in promoting global interactions between Industry and Academia. In addition to paper presentations and exhibits, InterPACK 2021 will include panel discussions, workshops, tutorials, keynotes and technology talks by prominent speakers, and a Joint Industry, National Lab, Academia poster session. **Abstracts (<400 words) for original papers are solicited in the general track areas of:**

Heterogeneous Integration:

Advanced Packaging, Die Stacking, Multichip Modules, Interconnect Technology, Substrate Technology, Through-Silicon Vias (TSV), Wafer Level Packaging (Fan-in, Fan-out), Panel Level Packaging, System in Package (SiP), Microsystems Integration, Integrated Photonics, RF Packaging, Advanced Materials and Processes, Chip Package Interaction, Modeling, Characterization and Reliability for Integrated Devices, Electronic Materials, Underfills, Molding Compounds, Substrates, Thermal Materials, Dielectrics.

Servers of the Future, and Edge to Cloud:

Data Centers & Energy Efficient Electronic Systems, Cloud Computing Hardware, Edge to Cloud Systems, Rack Level Cooling, Thermal Interface Materials & Thermal Underfills, Fans & Pumps, Thermosyphons & Refrigeration, Exaflop Computing Systems, Memory, Connectors, Advanced Substrates, Novel Cooling Techniques, Heat Exchangers, Device to System Level Packaging.

Flexible and Wearable Electronics:

Additive-printed electronics, Wearables, Internet of things, Asset Monitoring, Implantable Medical Devices, Microfluidics, Interconnects, Substrate Materials, Thin Die Handling, Non-Contact Processes. Sensors & Actuators, RF Resonators, Fabrication, Integration, Biosystems & Biomedicine, and Industry Perspectives. Reliability of devices, Interconnects, Materials Interactions, Chemical, Biological, and Physical Implications, System Level Reliability Issues, Materials characterization, Prognostics and Health Monitoring.

Photonics and Optics:

Photonics packaging, Optical integration, Thermal/mechanical challenges for optical photonics integration, LED Systems, High Speed Transceivers, LED Self-Heating on the External Quantum Efficiency, Thermomechanical Modeling of In-Package-Optics (IPO).

Power Electronics:

Wide Bandgap Electronic Devices and Semiconductor Packaging, Electro-Thermal Co-design, Power Electronics, Harsh Environment Sensors, High Temperature Electronics for Oil & Gas and Geothermal Energy, Novel Interconnects, Fracture, Fatigue, and Delamination of Interfaces and Interconnects, Thermal Materials for emerging applications (hypersonics, directed energy systems).

Multiscale Energy Transport/Conversion/Storage:

Energy Harvesting, Energy Storage, Energy Transport at Multiscales, Thermo-electrics, Photovoltaics, Multiphase Modeling Techniques in Multiscales, Machine learning-based thermal-fluid modeling.

Autonomous, Hybrid, and Electric Vehicles:

High Temperature Sensors, RADAR, LIDAR, Advanced Driver Assistance System (ADAS) Electronics, MEMS packaging, Control Systems, Electronic Materials, Nanosatellites, Unmanned Aerial Vehicle (UAV) Electronics, Hybrid Packaging, Prognostic Health Monitoring, Vehicle Charging, Wireless Power Transfer, Energy Conversion, Electric Drive Technologies, Motor Control Sensing, Battery Management.

Reliability of Electronic Packages and Systems:

Packaging Reliability for High Temperature Electronics, Electromigration, Reliability for Power Electronics Packaging, Reliability Testing for Harsh Environment Electronics, Advanced Doped Solders, Low-temperature Solders, Solder Joint Reliability, Reliability Issues in Opto-Electronics, Reliability Modelling and Simulation, Reliability Test Methods, Thermomechanical Stress and Device Reliability, Reliability in Hermetic Packages, digital twin, prognostics and health management.

Nano-scale Thermal Transport and Materials:

1D and 2D Nanomaterials, Nano-scale Conjugate Heat Transfer, Thermal Interface Resistance at Nano-scales, Experimental Methods in Nano-scale Thermal Transport, NEMS.

PUBLICATION SCHEDULE

Abstract Submission	March 8, 2021
Draft Paper Submission	May 7, 2021
Draft Paper Decisions	June 4, 2021

Revised Paper Decisions	June 28, 2021
Posters/Presentation Only Abstracts	July 5, 2021
Final Paper Submission	July 16, 2021

ASME SETTING THE STANDARD

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